

STS12N3LLH5

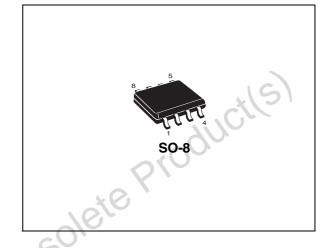
N-channel 30 V, 0.0068 Ω 12 A, SO-8 STripFET™ V Power MOSFET

Datasheet — production data

Features

Туре	V _{DSS}	R _{DS(on)} max	I _D
STS12N3LLH5	30 V	< 0.0075 Ω	12 A ⁽¹⁾

- 1. The value is rated according $R_{thj\text{-pcb}}$
- \blacksquare R_{DS(on)} * Q_g industry benchmark
- Extremely low on-resistance R_{DS(on)}
- Very low switching gate charge
- High avalanche ruggedness
- Low gate drive power losses



Application

Switching applications

Description

This device is an N-channel Power MOSFET developed using STMicroelectronics' STripFETTMV technology. The device has been optimized to achieve very low on-state resistance, contributing to an FOM that is among the best in its class.

Figure 1. Internal schematic diagram

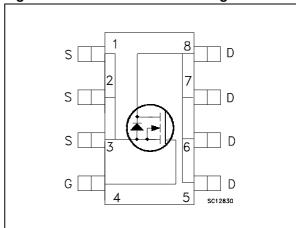


Table 1. Device summary

Order code	Marking	Package	Packaging
STS12N3LLH5	12D3L	SO-8	Tape and reel

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STS12N3LLH5 **Electrical ratings**

Electrical ratings 1

Table 2. **Absolute maximum ratings**

Symbol	Parameter	Value	Unit				
V _{DS}	Drain-source voltage (V _{GS} = 0)	30	V				
V _{GS}	Gate-source voltage +22/-20						
I _D ⁽¹⁾	Drain current (continuous) at T _C = 25 °C	12	Α				
I _D ⁽¹⁾	Drain current (continuous) at T _C =100 °C	8.75	Α				
I _{DM} ⁽²⁾	Drain current (pulsed)	48	Α				
$P_{TOT}^{(2)}$ Total dissipation at $T_C = 25 ^{\circ}C$ 2.7 W							
Derating factor 0.02 W/°C							
T _J	Operating junction temperature Storage temperature	-55 to 150	°C				
The value is rated according R _{thj-pcb} Pulse width limited by safe operating area							
Table 3.	Thermal resistance		1				

^{1.} The value is rated according $R_{\mbox{\scriptsize thj-pcb}}$

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R _{thj-pcb} ⁽¹⁾	Thermal resistance junction-ambient	47	°C/W

on Figure 1080 Proof 1. When mounted on FR-4 board of 1inch 2 , 2oz Cu, t < 10sec

^{2.} Pulse width limited by safe operating area

Electrical characteristics STS12N3LLH5

2 Electrical characteristics

(T_{CASE}=25°C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	30			٧
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V _{DS} = max rating, V _{DS} =max rating @125 °C			1 10	μ Α μ Α
I _{GSS}	Gate body leakage current (V _{DS} = 0)	V _{GS} = +22/-20 V			±100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	40		V
R _{DS(on)}	Static drain-source on- resistance	V_{GS} = 10 V, I_{D} = 6 A V_{GS} = 4.5 V, I_{D} = 6 A		0.0068 0.0084	0.0075 0.0092	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} = 25 V, f=1 MHz, V _{GS} =0	-	1290 240 32		pF pF pF
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD} =15 V, I_{D} = 12 A V_{GS} = 4.5 V Figure 14	-	8 3.6 3.4		nC nC nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
$\begin{array}{c} t_{d(on)} \\ t_{r} \\ t_{d(off)} \\ t_{f} \end{array}$	Turn-on delay time Rise time Turn-off delay time Fall time	V_{DD} =15 V, I_{D} = 6 A, R_{G} =4.7 Ω , V_{GS} =10 V Figure 13	-	8.6 11.2 32.4 6	-	ns ns ns ns

STS12N3LLH5 **Electrical characteristics**

Table 7. Source drain diode

Symbol Parameter Test conditions Min Typ. Max Unit	Table 7.	Source drain diode	T				
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		Source-drain current		-		12	Α
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		48	Α
Q _{rr} Reverse recovery charge di/dt = 100 A/μs, - 15 nC		Forward on voltage	I _{SD} = 12 A, V _{GS} =0	-		1.1	V
		Reverse recovery time I _{SD} = 12 A, 22					
I _{RRM} Reverse recovery current V _{DD} = 25 V, I _J =150 °C 1.4 A 1. Pulse width limited by safe operating area 2. Pulsed: pulse duration=300μs, duty cycle 1.5%							
 Pulse width limited by safe operating area Pulsed: pulse duration=300μs, duty cycle 1.5% 	IRRM	Reverse recovery current	V _{DD} = 25 V, IJ=150 °C		1.4		А
Droo.					111	J \	

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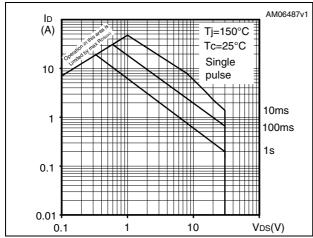
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Electrical characteristics STS12N3LLH5

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

Figure 3. Thermal impedance



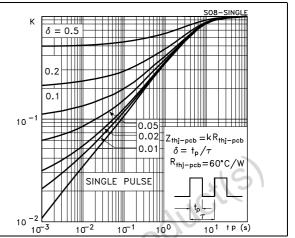
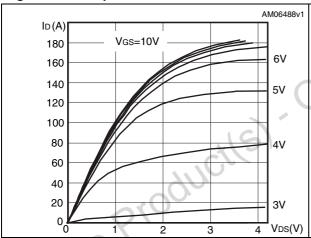


Figure 4. Output characteristics

Figure 5. Transfer characteristics



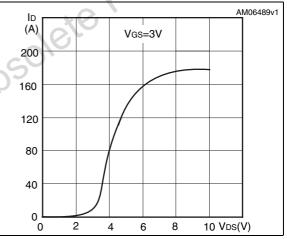
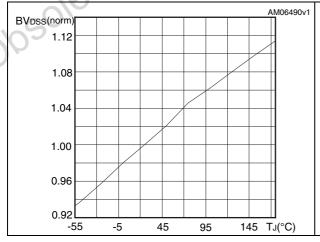
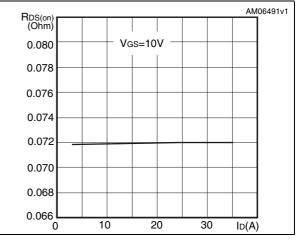


Figure 6. Normalized B_{VDSS} vs temperature

Figure 7. Static drain-source on-resistance





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Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations

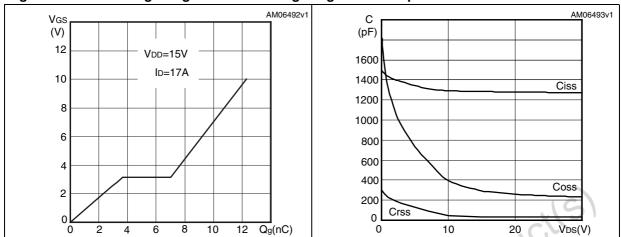


Figure 10. Normalized gate threshold voltage Figure 11. Normalized on-resistance vs vs temperature temperature

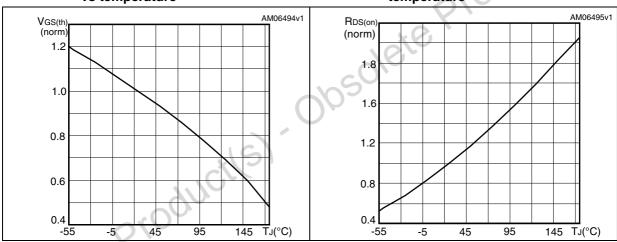
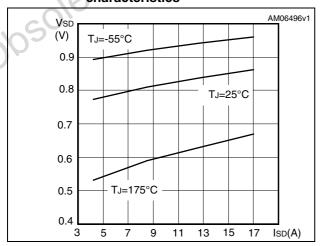


Figure 12. Source-drain diode forward characteristics



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Test circuits STS12N3LLH5

3 Test circuits

Figure 13. Switching times test circuit for resistive load

Figure 14. Gate charge test circuit

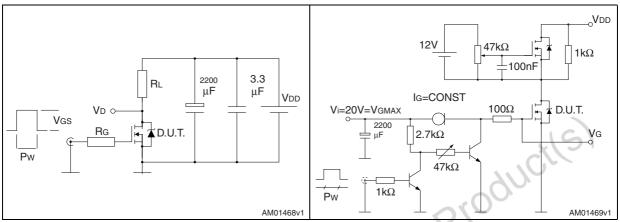


Figure 15. Test circuit for inductive load switching and diode recovery times

Figure 16. Unclamped inductive load test circuit

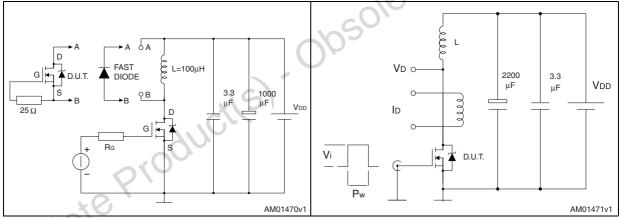
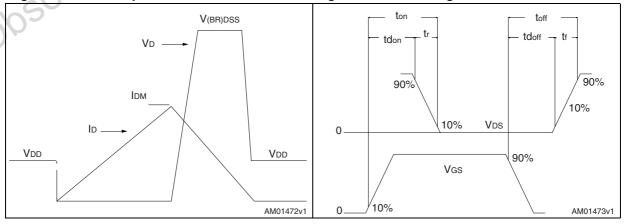


Figure 17. Unclamped inductive waveform

Figure 18. Switching time waveform



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4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

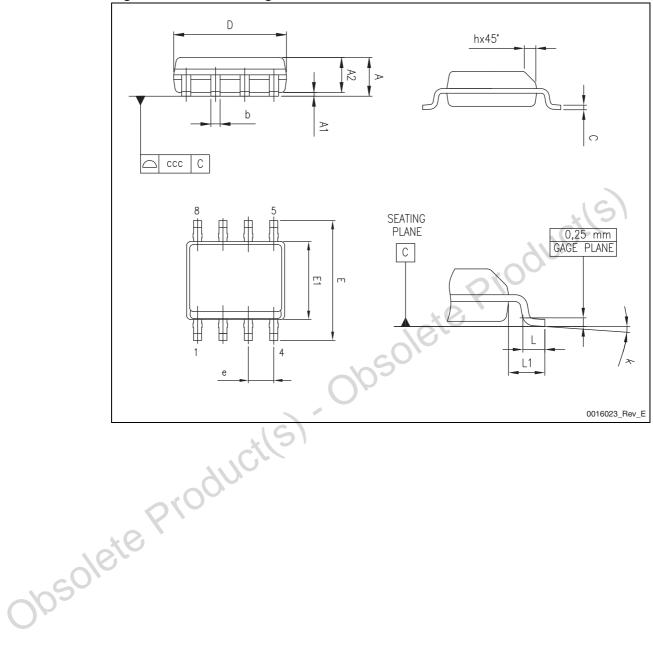
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Table 8. SO-8 mechanical data

	Dim.		mm	
	Dilli.	Min.	Тур.	Max.
	А			1.75
	A1	0.10		0.25
	A2	1.25		
	b	0.28		0.48
	С	0.17		0.23
	D	4.80	4.90	5.00
	E	5.80	6.00	6.20
	E1	3.80	3.90	4.00
	е		1.27	00.0
	h	0.25	0	0.50
	L	0.40	40,	1.27
	L1		1.04	
	k	0°	60,	8°
	ccc		102	0.10
	Pro	ductis		
Jbsolf	ate .			

Figure 19. SO-8 drawing



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Revision history STS12N3LLH5

5 Revision history

Table 9. Document revision history

	Date	Revision	Changes
	19-Feb-2010	1	First release.
	01-Jul-2011	2	Datasheet status promoted from preliminary data to datasheet. Modified: <i>Table 2</i> and <i>4</i> .
	07-Jun-2012	3	Updated mechanical data. Minor text changes.
Obsole	te Pro	ductl	Minor text changes.

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